

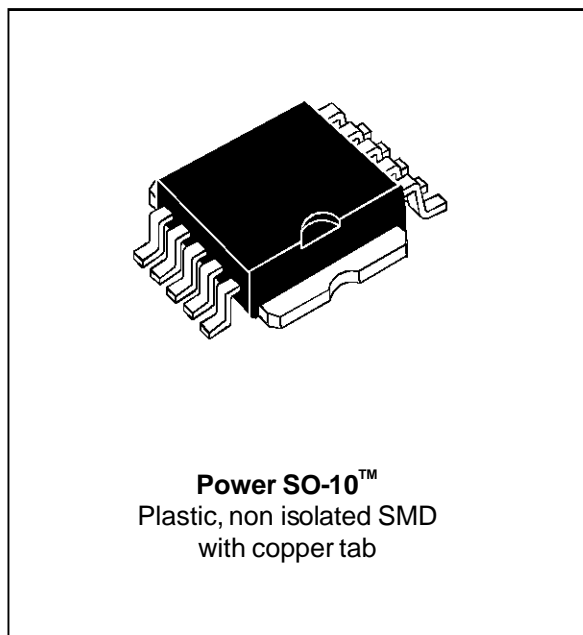
FEATURES

- TRANSIENT VOLTAGE SUPPRESSOR DIODE ESPECIALLY DESIGNED FOR LOAD DUMP EFFECT PROTECTION
- HIGH SURGE CURRENT CAPABILITY : 30 A / 40 ms EXPONENTIAL WAVE
- COMPLIANT WITH MAIN STANDARDS SUCH AS:
-ISO / DTR 7637
-SAEJ 1113A ...
- SURFACE MOUNT TECHNOLOGY COMPATIBLE

DESCRIPTION

Transient voltage suppressor diode especially developed for sensitive circuit protection in automotive systems such as dash board, car radios etc.

Its high surge current capability and instantaneous response to transients provide an efficient protection against the load dump effect.


ABSOLUTE MAXIMUM RATINGS ($-40^{\circ}\text{C} < T_{\text{amb}} < 85^{\circ}\text{C}$)

Symbol	Parameter		Value	Unit
V_{PP}	Repetitive peak pulse load dump overvoltage - 5 pulses (1 minute between each pulse) - (See note 1 and 2)		100	V
I_{FSM}	Non repetitive surge peak forward current	$t_p = 10\text{ms}$	120	A
T_{stg}	Storage junction temperature range		- 40 to + 150	$^{\circ}\text{C}$
T_j	Maximum operating junction temperature		150	$^{\circ}\text{C}$
T_l	Maximum lead temperature for soldering during 10 s		260	$^{\circ}\text{C}$

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{\text{th(j-c)}}$	Junction to case	1.2	$^{\circ}\text{C/W}$

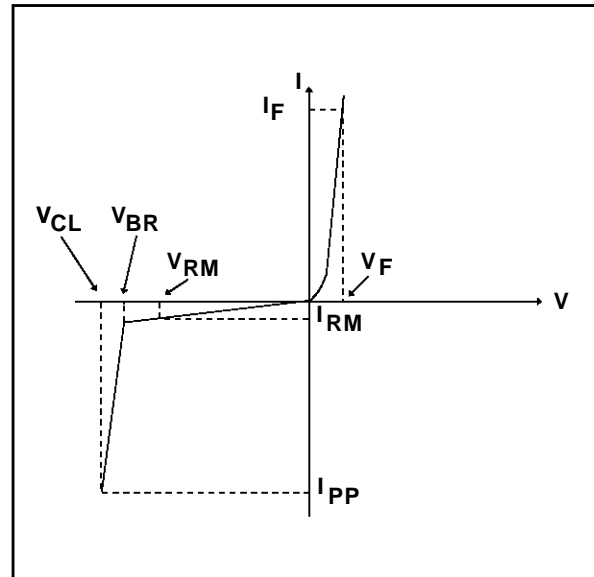
Note 1 : For surges greater than the maximum values, the diode will present a short-circuit Anode-Cathode

Note 2 : See load dump test generator circuit (page 4/10)

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ELECTRICAL CHARACTERISTICS

Symbol	Parameter
V_{RM}	Stand-off voltage.
V_{BR}	Breakdown voltage.
V_{CL}	Clamping voltage.
I_{PP}	Peak pulse current.
αT	Temperature coefficient of V_{BR} .
C	Capacitance
V_F	Peak forward voltage drop



Symbol	Test Conditions	Min.	Typ.	Max.	Unit
I_{RM}	$T_C = -40^\circ\text{C}$ $V_{RM} = 24\text{V}$ $T_C = 25^\circ\text{C}$ $T_C = 85^\circ\text{C}$			5 10 100	μA
V_{BR}	$T_C = 25^\circ\text{C}$ $I_R = 1\text{mA}$	25.5		32	V
V_F	$T_C = 25^\circ\text{C}$ $I_{FM} = 10\text{A}$		0.9		V
V_{CL}	$T_C = -40^\circ\text{C}$ $I_{PP} = 30\text{A}$ $T_C = 25^\circ\text{C}$ (Note 2) $T_C = 85^\circ\text{C}$			36 38 40	V
αT				9	$10^{-4}/^\circ\text{C}$
C	F = 1MHz $V_R = 0\text{V}$		8000		pF

Note 2 : See load dump test generator circuit (page 4/10)

Fig.1 : Peak pulse power versus exponential pulse duration (T_J initial = 85°C).

Fig.2 : Clamping voltage versus peak pulse current (T_J initial = 85°C). Exponential waveform $t_p = 40\text{ms}$ and $t_p = 1\text{ms}$.

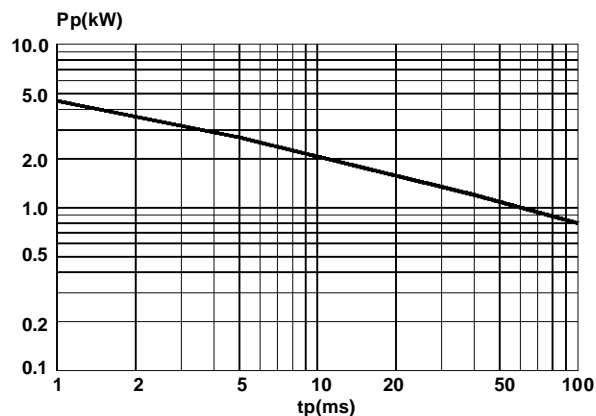


Fig.3 : Peak pulse current versus exponential pulse duration (T_j initial = 85°C).

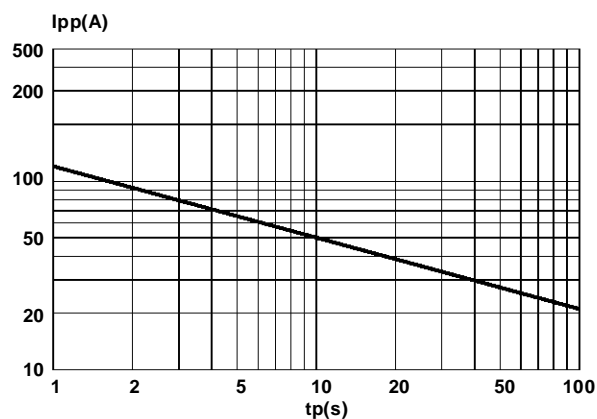


Fig.4 : Relative variation of peak pulse power versus junction temperature.

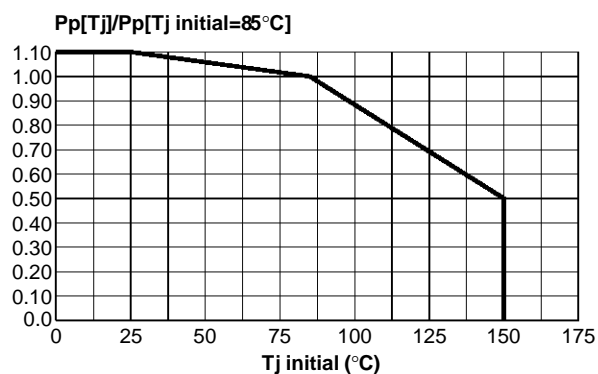


Fig.5 : Relative variation of thermal impedance junction to case versus pulse duration.

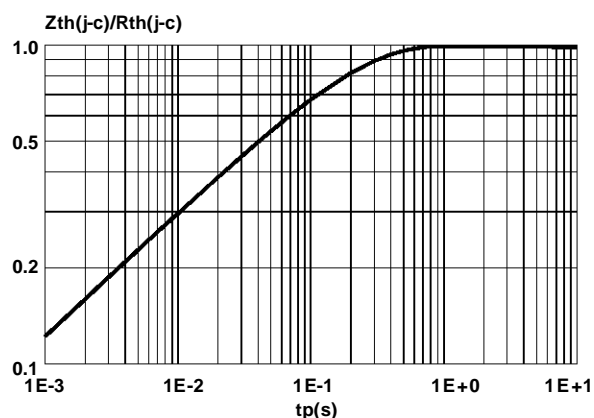


Fig.6 : Peak forward voltage drop versus peak forward current (typical values).

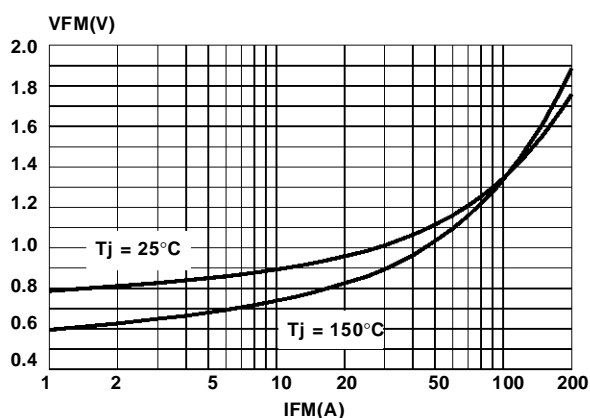
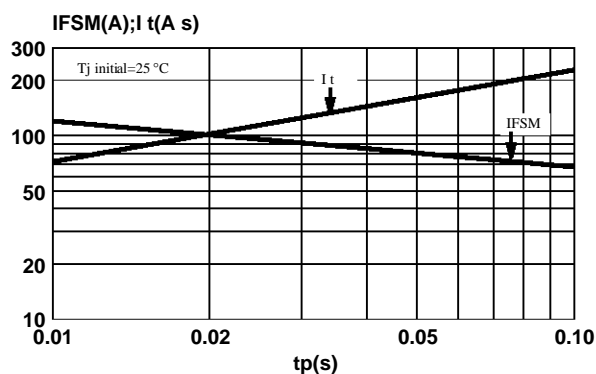


Fig. 7 : Non repetitive surge peak current versus pulse duration (sinusoidal pulse) and corresponding value of I_{2t} .

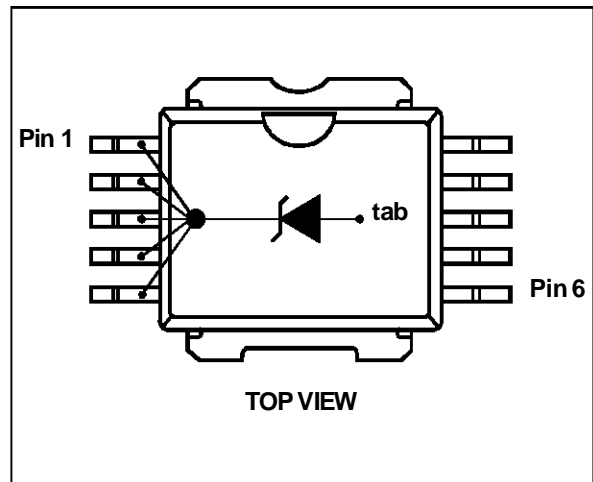


LDP24M

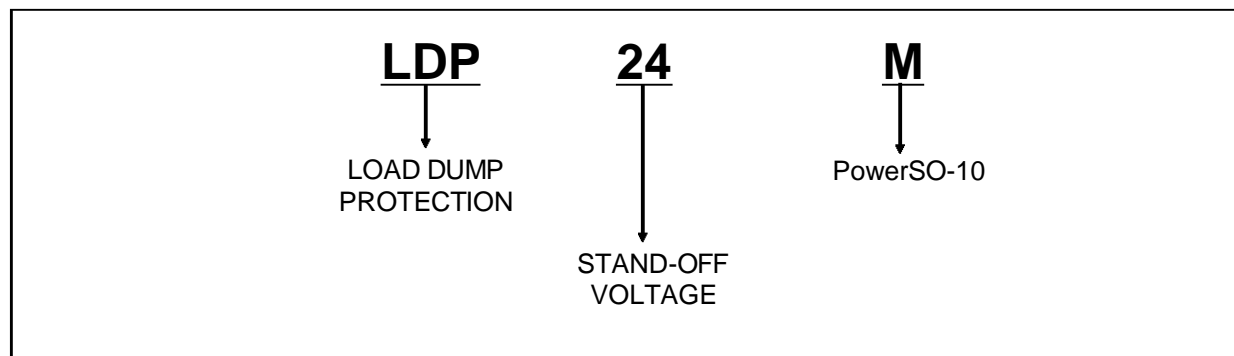
PIN OUT configuration :

- Cathode : Pins 1 to 5
- Anode : Connected to base tab.
- N.C. : Pins 6 to 10.

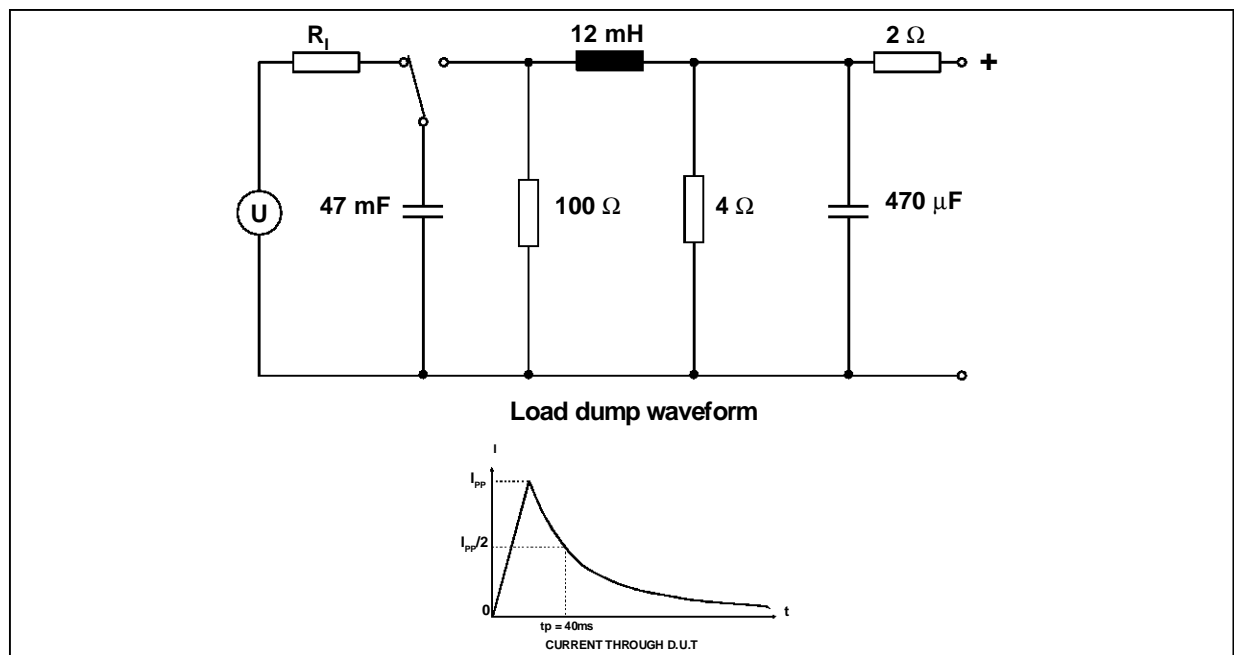
Marking : Logo, date code, LDP24M



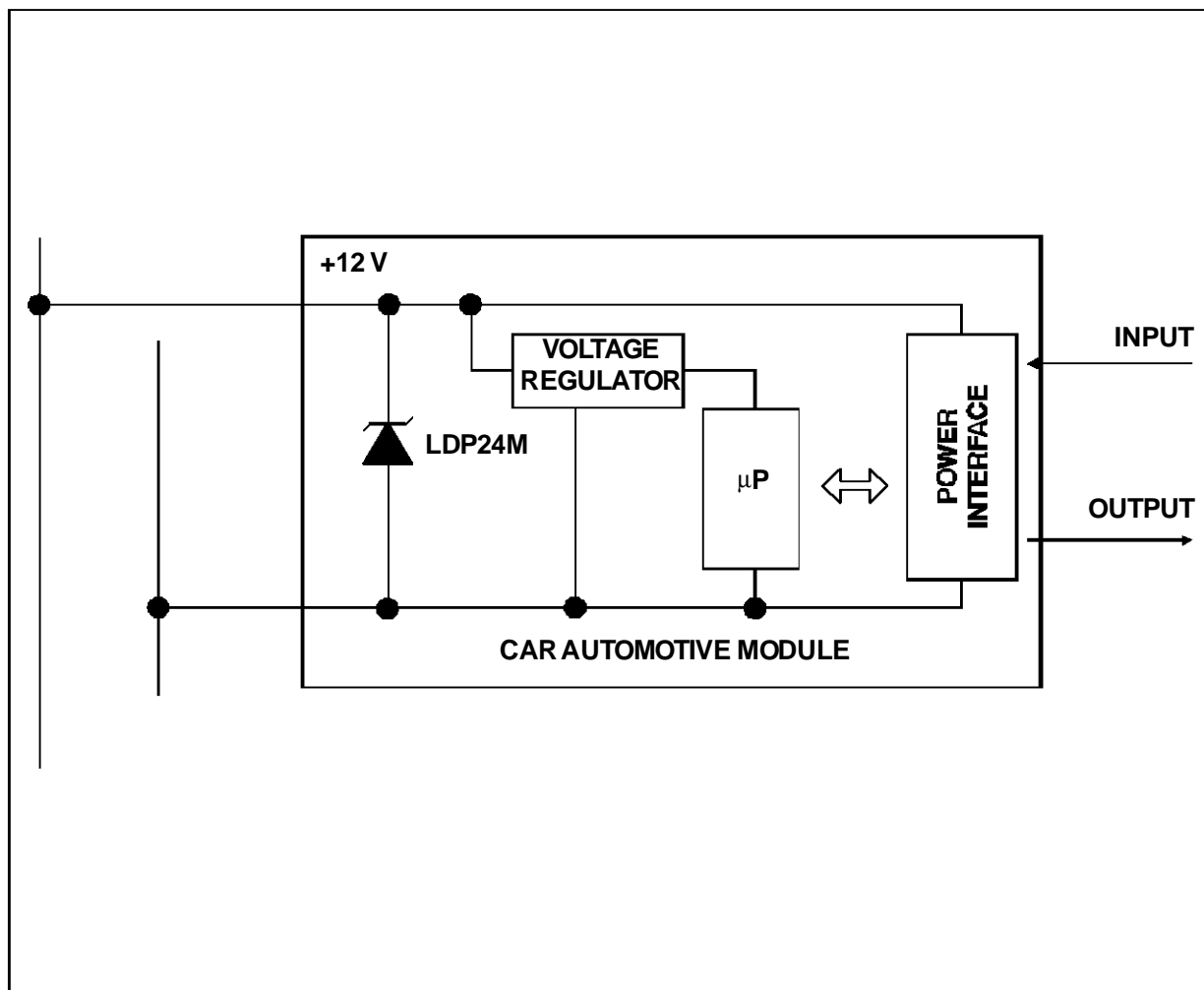
ORDER CODE



LOAD DUMP TEST GENERATOR CIRCUIT (SCHAFFNER NSG 506C)



BASIC APPLICATION



The drawing above shows the typical use of the LDP24M.

This provides protection of the +12 V supply rail directly on the car electronic module.

This overvoltage suppressor was developed to immunize the sensitive parts from both long duration (load dump) and short duration (ESD) surges.

SOLDERING RECOMMENDATION

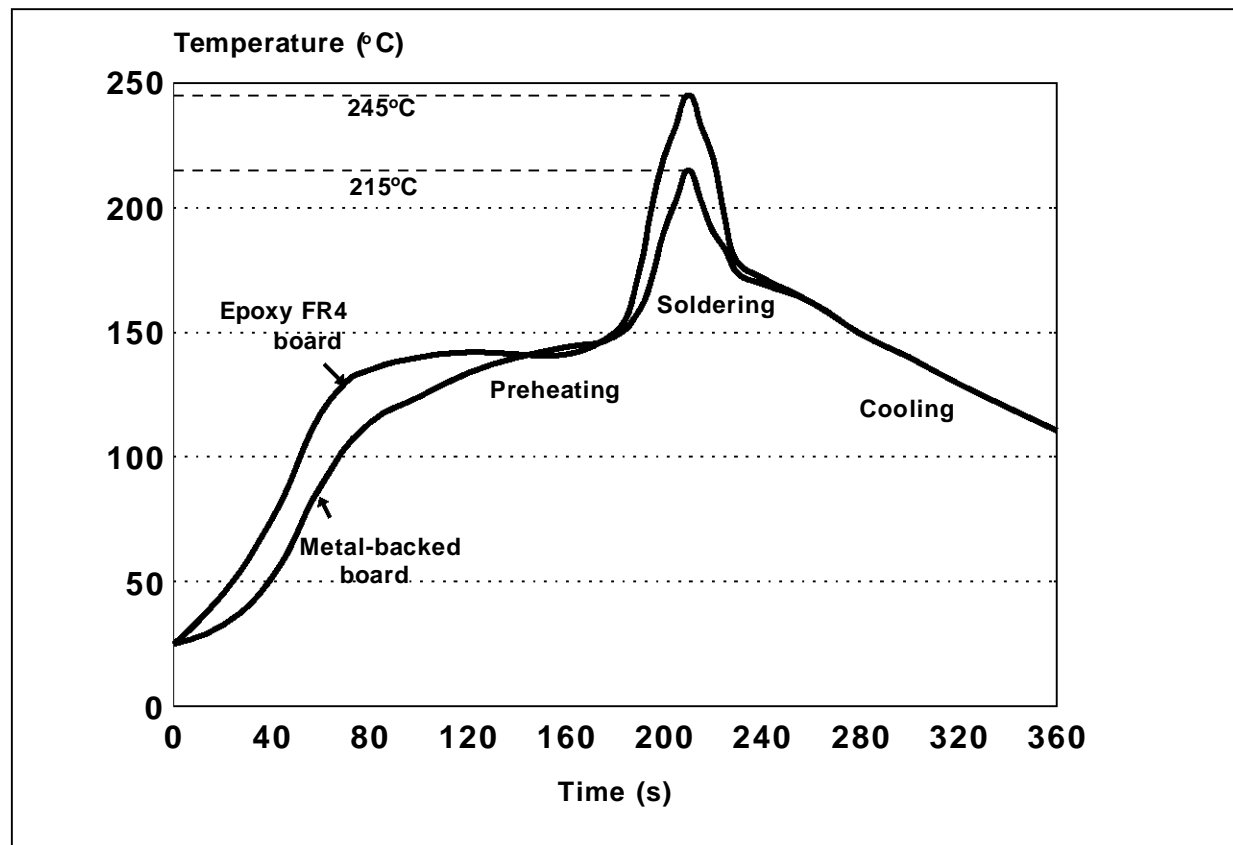
The soldering process causes considerable thermal stress to a semiconductor component. This has to be minimized to assure a reliable and extended lifetime of the device. The PowerSO-10 package can be exposed to a maximum temperature of 260°C for 10 seconds. However a proper soldering of the package could be done at 215°C for 3 seconds. Any solder temperature profile should be within these limits. As reflow techniques are most common in surface mounting, typical heating profiles are given in Figure 1, either for mounting on FR4 or on metal-backed boards. For each particular board, the appropriate heat profile has to be adjusted experimentally. The present proposal is just a starting point. In any case, the following precautions have to be considered :

- always preheat the device
- peak temperature should be at least 30 °C higher than the melting point of the solder alloy chosen
- thermal capacity of the base substrate

Voids pose a difficult reliability problem for large surface mount devices. Such voids under the package result in poor thermal contact and the high thermal resistance leads to component failures. The PowerSO-10 is designed from scratch to be solely a surface mount package, hence symmetry in the x- and y-axis gives the package excellent weight balance. Moreover, the PowerSO-10 offers the unique possibility to control easily the flatness and quality of the soldering process. Both the top and the bottom soldered edges of the package are accessible for visual inspection (soldering meniscus).

Coplanarity between the substrate and the package can be easily verified. The quality of the solder joints is very important for two reasons : (I) poor quality solder joints result directly in poor reliability and (II) solder thickness affects the thermal resistance significantly. Thus a tight control of this parameter results in thermally efficient and reliable solder joints.

Fig 1 : Typical reflow soldering heat profile



SUBSTRATES AND MOUNTING INFORMATION

The use of epoxy FR4 boards is quite common for surface mounting techniques, however, their poor thermal conduction compromises the otherwise outstanding thermal performance of the PowerSO-10. Some methods to overcome this limitation are discussed below.

One possibility to improve the thermal conduction is the use of large heat spreader areas at the copper layer of the PC board. This leads to a reduction of thermal resistance to 35 °C for 6 cm² of the board heatsink (see fig. 2).

Use of copper-filled through holes on conventional FR4 techniques will increase the metallization and

decrease thermal resistance accordingly. Using a configuration with 16 holes under the spreader of the package with a pitch of 1.8 mm and a diameter of 0.7 mm, the thermal resistance (junction - heatsink) can be reduced to 12°C/W (see fig. 3). Beside the thermal advantage, this solution allows multi-layer boards to be used. However, a drawback of this traditional material prevents its use in very high power, high current circuits. For instance, it is not advisable to surface mount devices with currents greater than 10 A on FR4 boards. A Power Mosfet or Schottky diode in a surface mount power package can handle up to around 50 A if better substrates are used.

Fig 2 : Mounting on epoxy FR4 head dissipation by extending the area of the copper layer

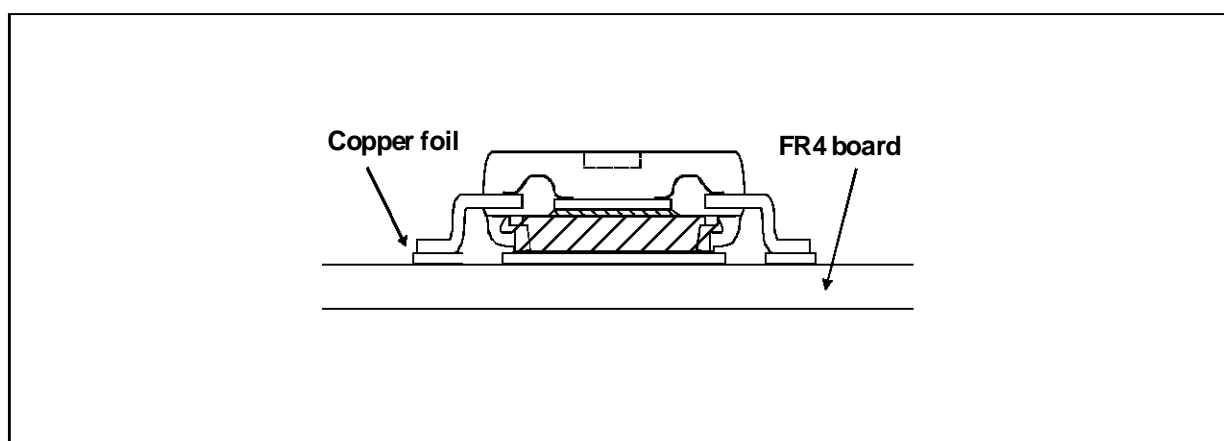
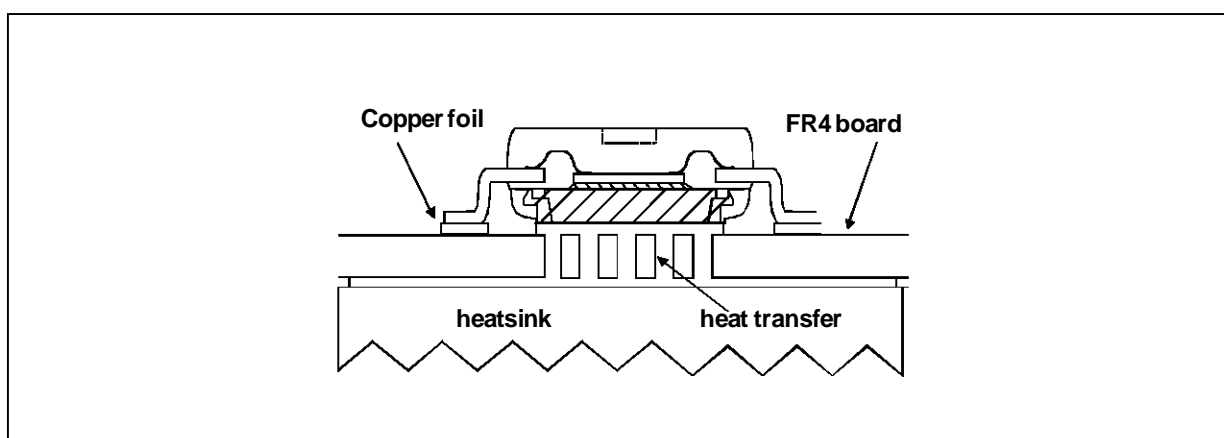


Fig 3 : Mounting on epoxy FR4 by using copper-filled through holes for heat transfer



LDP24M

A new technology available today is IMS - an Insulated Metallic Substrate. This offers greatly enhanced thermal characteristics for surface mount components. IMS is a substrate consisting of three different layers, (I) the base material which is available as an aluminium or a copper plate, (II) a thermal conductive dielectrical layer and (III) a copper foil, which can be etched as a circuit layer. Using this material a thermal resistance of 8°C/W with 40 cm² of board floating in air is achievable (see fig. 4). If even higher power is to be dissipated an external heatsink could be applied which leads to an $R_{th(j-a)}$ of 3.5°C/W (see Fig. 5), assuming that R_{th} (heatsink-air) is equal to R_{th} (junction-heatsink). This is commonly applied in practice, leading to reasonable heatsink dimensions. Often power devices are defined by

considering the maximum junction temperature of the device. In practice, however, this is far from being exploited. A summary of various power management capabilities is made in table 1 based on a reasonable delta T of 70°C junction to air.

The PowerSO-10 concept also represents an attractive alternative to C.O.B. techniques. PowerSO-10 offers devices fully tested at low and high temperature. Mounting is simple - only conventional SMT is required - enabling the users to get rid of bond wire problems and the problem to control the high temperature soft soldering as well. An optimized thermal management is guaranteed through PowerSO-10 as the power chips must in any case be mounted on heat spreaders before being mounted onto the substrate.

Fig 4 : Mounting on metal backed board

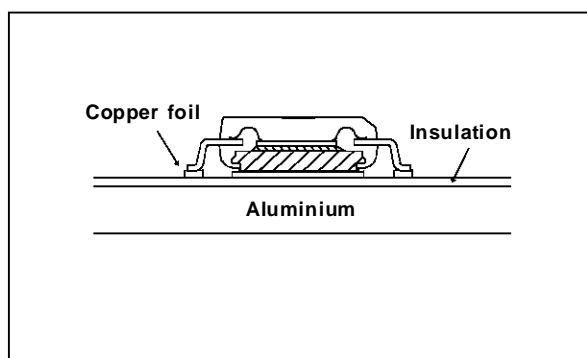


Fig 5 : Mounting on metal backed board with an external heatsink applied

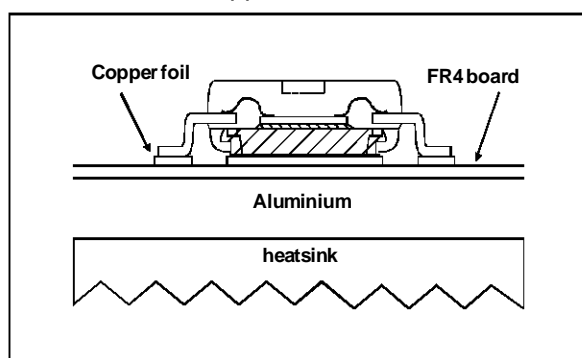
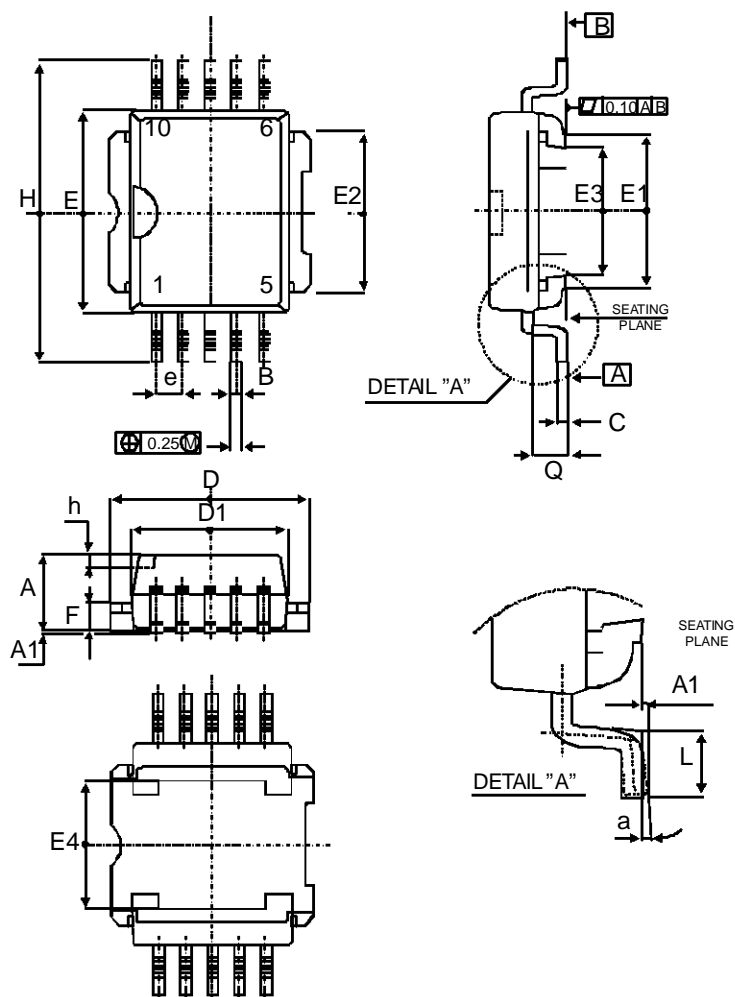


TABLE 1

PowerSo-10 package mounted on	$R_{th(j-a)}$	P Diss
1.FR4 using the recommended pad-layout	50 °C/W	1.5 W
2.FR4 with heatsink on board (6cm ²)	35 °C/W	2.0 W
3.FR4 with copper-filled through holes and external heatsink applied	12 °C/W	5.8 W
4. IMS floating in air (40 cm ²)	8 °C/W	8.8 W
5. IMS with external heatsink applied	3.5 °C/W	20 W

PACKAGE MECHANICAL DATA

PowerSO-10 (plastic)

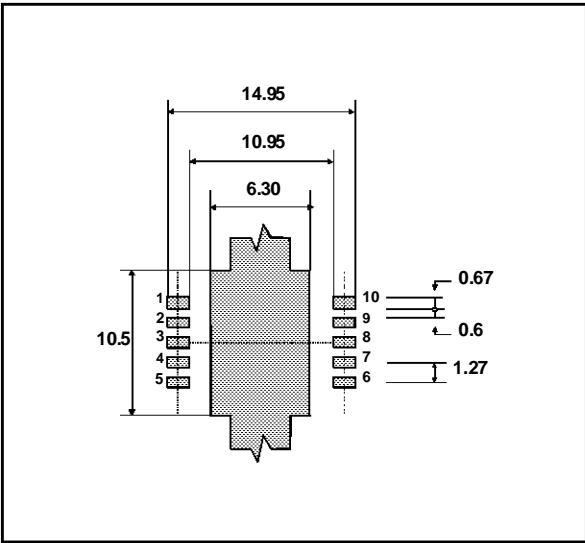


REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	3.35		3.65	0.131		0.143
A1	0.00		0.10	0.00		0.0039
B	0.40		0.60	0.0157		0.0236
C	0.35		0.55	0.0137		0.0217
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.299
E	9.30		9.50	0.366		0.374
E1	7.20		7.40	0.283		0.291
E2	7.20		7.60	0.283		0.299

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
E3	6.10		6.35	0.240		0.250
E4	5.90		6.10	0.232		0.240
e		1.27			0.05	
F	1.25		1.35	0.0492		0.0531
H	13.80		14.40	0.543		0.567
h		0.50			0.019	
L	1.20		1.80	0.0472		0.0708
Q		1.70			0.067	
a	0°		8°	0°		8°

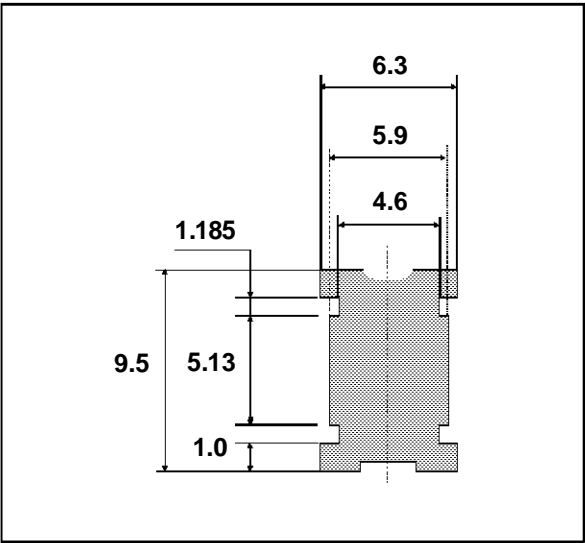
LDP24M

**FOOT PRINT
MOUNTING PAD LAYOUT
RECOMMENDED**



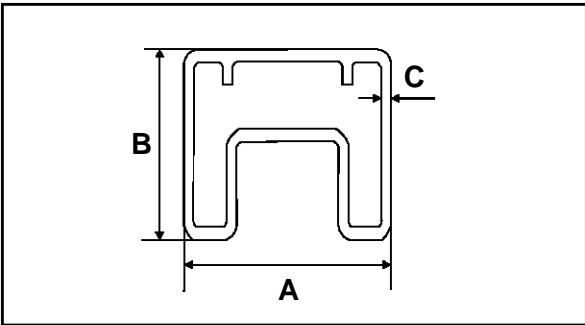
Dimensions in millimeters

HEADER SHAPE



Dimensions in millimeters

SHIPPING TUBE



	DIMENSIONS (mm)
	TYP
A	18
B	12
C	0,8
Length tube	532
Quantity per tube	50

Surface mount film taping : contact sales office

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